

HZL6.8Z4

Silicon Planar Zener Diode for Surge Absorb

REJ03G0410-0100 Rev.1.00 Oct 01, 2004

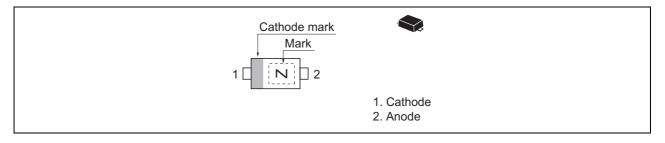
Features

- Low capacitance (C = 4.0 pF max) and can protect ESD of signal line.
- Extremely small Flat Package (EFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HZL6.8Z4	Z	EFP

Pin Arrangement





Absolute Maximum Ratings

(Ta = 25°C)

ltem	Symbol	Value	Unit
Power dissipation	Pd *	100	mW
Junction temperature	Тј	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: See Fig.2.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	6.47	-	7.00	V	$I_Z = 5 \text{ mA}, 40 \text{ ms pulse}$
Reverse current	I _R	—	-	2	μΑ	V _R = 3.5 V
Capacitance	С	—	-	4.0	pF	$V_R = 0 V, f = 1 MHz$
Dynamic resistance	r _d	—	-	30	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *1	—	8	_	_	kV	C = 150 pF, R = 330 Ω , Both Forward and reverse direction 10 pulse

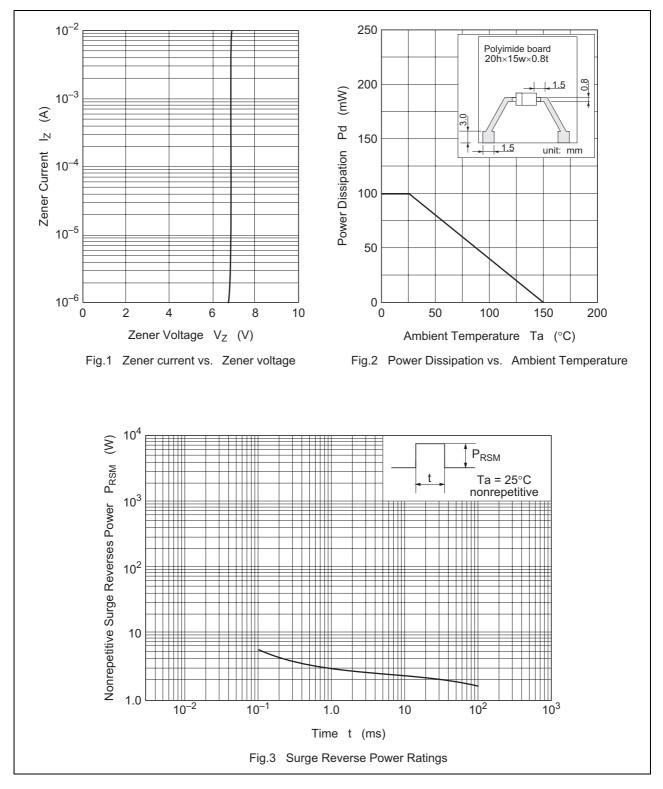
Notes: 1. Failure criterion ; $I_R > 2 \ \mu A$ at $V_R = 3.5 \ V$.

2. Please do not use the soldering iron due to avoid high stress to the EFP package.

3. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

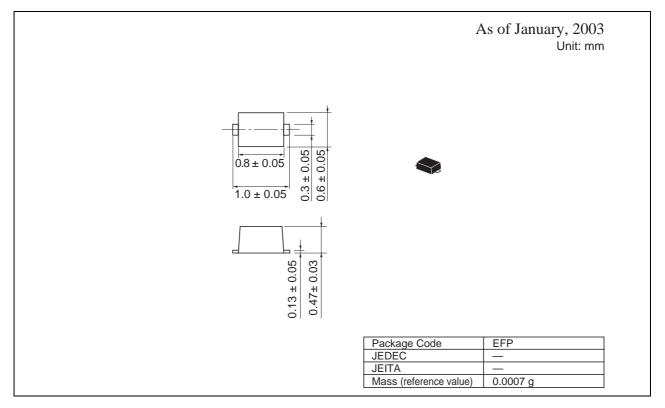


Main Characteristic





Package Dimensions





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